Supplementary Information:

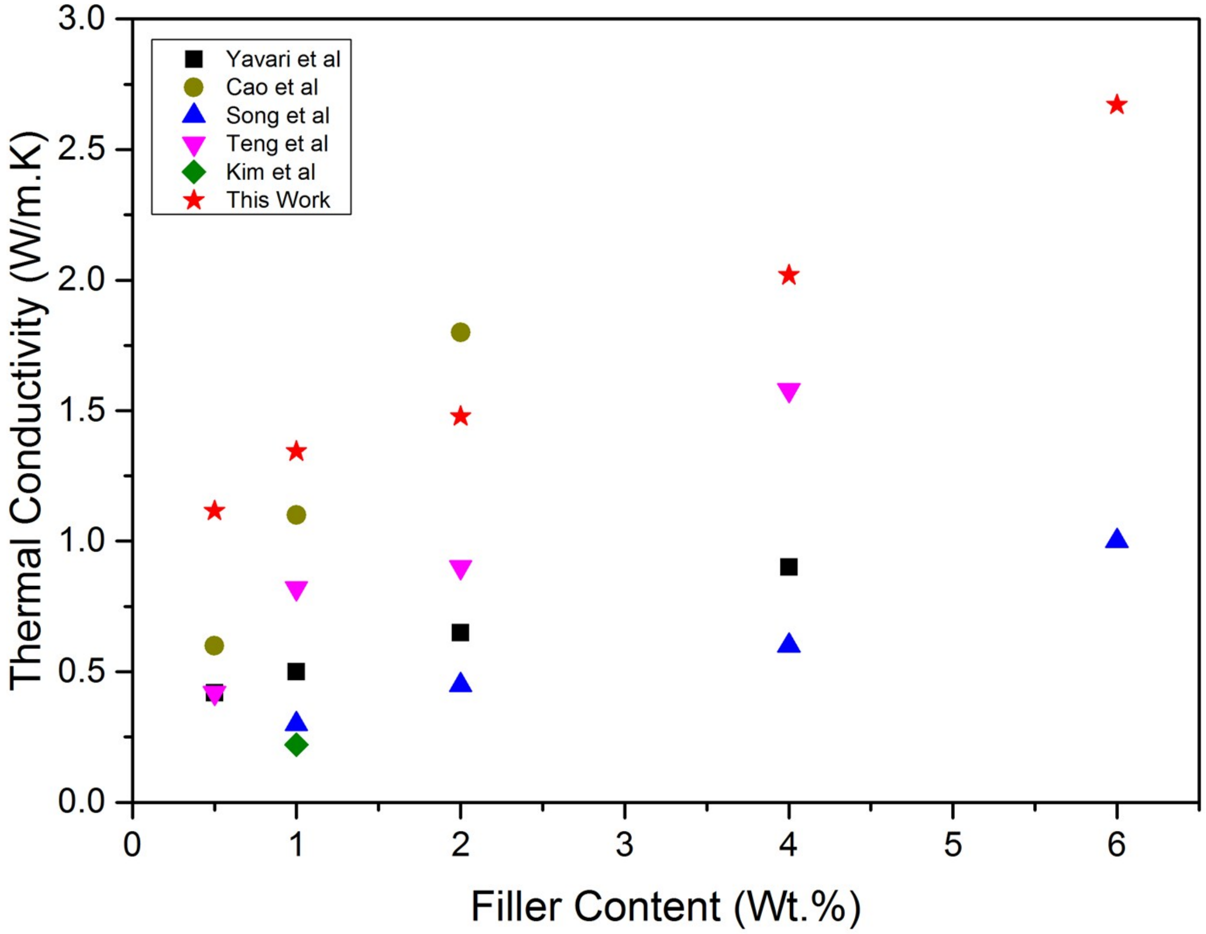

Figure S1: Comparison of thermal conductivity with other related work.

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